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⑦① Applicant: **Hitachi Chemical Co., Ltd., 1-1,**
Nishi-shinjuku 2-chome Shinjuku-ku, Tokyo 160 (JP)

⑦② Inventor: **Tsukagoshi, Isao, 1015-8, Oaza Nunogawa,**
Shimodate-shi (JP)
Inventor: **Yamaguchi, Yutaka, 7941-169, Yuuki, Yuuki-shi**
(JP)
Inventor: **Hazama, Keiji, 568, Hitotonoya, Oyama-shi (JP)**
Inventor: **Nakayama, Tadamitsu, 11-33, Baba-6-chome,**
Tsurumi-ku Yokohama (JP)

⑦④ Representative: **Goldin, Douglas Michael et al, J.A.**
KEMP & CO. 14, South Square Gray's Inn, London
WC1R 5EU (GB)

⑤④ **Anisotropic-electroconductive adhesive film and circuit connecting method using the same.**

⑤⑦ An anisotropic-electroconductive adhesive film containing a small quantity of electroconductive particles of defined shape in an adhesive component layer of limited thickness is useful for connecting micro-sized circuits, etc. due to its anisotropy in electroconductivity and good transparency.

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ANISOTROPIC-ELECTROCONDUCTIVE ADHESIVE FILM AND
CIRCUIT CONNECTING METHOD USING THE SAME

1 The present invention relates to an anisotropic-
electroconductive adhesive film which is electrically
conductive only in the direction perpendicular to the
surface thereof and not in any direction parallel to the
5 surface. The invention also relates to a circuit connect-
ing method employing such a film.

Solders and electroconductive adhesives have
so far been used widely as means of connecting large scale
integrated circuits (LSI) or electrodes of liquid crystal
10 display elements (LCD) to printed circuit boards and of
bonding flexible flat cables (FFC) to external connecting
terminals of various devices.

However, with the miniaturization of electronic
parts and the size reduction of connecting circuits, it
15 has become extremely difficult to connect circuits to
one another without causing short circuit between neighbor-
ing parts of the circuits in particular when connecting
terminals or the like are aligned at fine pitches.

In addition, soldering has a drawback of low
20 reliability in adhesion due to hard and brittle pro-
perties thereof, that is, the liability of bonded parts
to be readily separated by a shock or the like.

Electroconductive adhesives, on the other hand,
are expensive because conductive fillers need to be in-
25 corporated to high concentrations of at least 20% by

1 volume into adhesives in order to obtain necessary electric
conductivity. Further drawbacks of conductive adhesives
are that variation in the conductivity is caused by such a
factor as the precipitation of the filler during storage
5 or difficulty in uniform coating thereof and that environ-
mental pollution due to the contained organic solvent
may occur.

An example of the attempts to eliminate these
drawbacks is the method disclosed in Japanese Patent
10 Application Kokai (Laid-Open) No. 147,732/78, which com-
prises applying a conductive adhesive prepared by incorpo-
rating 5 to 25% by weight of electroconductive carbon
black as an electroconductive filler into a heat-sensitive
adhesive and conducting an electric current through the
15 layer of the applied adhesive to generate Joule's heat,
thereby completing bonding.

According to this method, however, the upper
limit of the electroconductivity is $10^{\circ}\Omega\text{-cm}^{-1}$, the ap-
pearance is black in color, and the transparency is lost
20 completely, since carbon is used as the electroconductive
filler. Moreover, the bonding operation requires a long
time ranging from 10 minutes to 10 hours and the work-
ability is inferior, since the adhesion is achieved with
Joule's heat.

25 Adhesive tapes having electroconductive
anisotropy are also known which are prepared by dispersing
metal particles as electroconductive filler particles
in a polymer binder (Japanese Patent Application Kokai

1 (Laid-Open) No. 101040/76). Such adhesive tapes, however,
are inferior in adhesive properties and transparency,
since conductive fillers such as metal particles need to
be incorporated in large quantities of at least 10% by
5 volume in order to secure the necessary electroconduc-
tivity.

Further, for circuit connecting purposes, there
are used in practice connecting materials having aniso-
tropic-electroconductivity which materials are produced
10 by linear alignment of metal wires, carbon filaments, or
carbon particles in polymers, for example, silicone
rubber. However, these connecting materials have a number
of drawbacks in that the minimum separation width of the
conductors or insulators is as large as 0.2 mm at best,
15 thus the use of these materials for connecting fine
circuits is limited, compression pressure should always
be applied in order to maintain the connection in a good
state and this requires a special fixing means, which
results in restricting equipment designs, and the materials
20 themselves are opaque so that the adjustment of relative
positions of circuits is complicated when the circuits
are superposed and connected together.

Thus, an object of the present invention is to
provide an anisotropic-electroconductive adhesive film
25 which permits achieving with simple operation the electro-
conductive connection between two groups of connecting
terminals which face each other and are each aligned at
fine pitches. Another object of the invention is to

1 provide a method for connecting circuits by using said
film.

According to the invention, there is provided
an anisotropic-electroconductive adhesive film comprising
5 an adhesive component and electroconductive particles,
characterized in that the adhesive component contains 0.1
to 10% by volume of electroconductive particles having
an average particle size of 1 to 50 μm with a ratio of the
minimum diameter to the maximum diameter of each particle
10 being 0.5 to 1.0, and the thickness of an adhesive layer
is at least 110% of the average particle size of the
electroconductive particles and not more than 100 μm .

In the attached drawings, Fig. 1 is a cross-
sectional view of the anisotropic-electroconductive ad-
15 hesive film according to the invention, Fig. 2 is a
perspective view showing the connected state of a group of
connecting terminals formed on a circuit board and Fig. 3
is a schematic cross-sectional view showing the concept of
the connecting operations.

20 This invention is explained in detail referring
to the drawings.

Fig. 1 shows the fundamental construction of the
anisotropic-electroconductive adhesive film according to
the invention. As shown in Fig. 1, the adhesive film
25 comprises an adhesive layer 2 of bonding material and
electroconductive particles 3 dispersed therein. The
adhesive layer 2 is an electrical insulator and has
functions of holding electroconductive particles 3 with

1 dispersed state and adhering a printed circuit board or
the like. The layer 2 undergoes plastic deformation on
applying pressure with or without heating, and this brings
electroconductive particles into contact one with another
5 along the direction of the pressure application so as
to maintain electric conductivity permanently.

Fig. 2 shows the state wherein a connecting
terminal 5 of a flexible printed circuit board 4 is
connected electrically with a connecting terminal 7 of a
10 flexible flat cable 6 by using such an adhesive film as
shown in Fig. 1. In this case, the opposing pairs of
connecting terminals 5-7, 5'-7', ... are each in an
electrically conductive state while the communications
between the neighboring terminals 5 and 5', ... and be-
15 tween the neighboring terminals 7 and 7', ... are each
in an electrically insulated state.

The adhesive film according to the invention has
an anisotropy in electrical conductivity between the
directions perpendicular and parallel to the surface there-
20 of (hereinafter for convenience, the direction perpendic-
ular to the film surface is referred to as the "thickness
direction" and the directions parallel to the film surface
as the "plane direction". The film has a resistivity of
at least $10^6 \Omega\text{-cm}$ in the plane direction and a resisti-
25 vity of not more than $10^3 \Omega\text{-cm}$ in the thickness direc-
tion, exhibiting thus a great anisotropy in resistivity.
The adhesive film has a small minimum separation width
of resistance both in the plane and the thickness direction,

1 thus being good in resolution. That is, the minimum
insulation width in the film plane direction is 0.05 mm.
Moreover the application of the film can be accomplished
under both heat-sensitive and pressure-sensitive conditions.

5 Accordingly, the adhesive film offers good application
workability and strong adhesion as well as high electrical
conductivity and additionally has a considerably high
transparency.

The above-mentioned features of the film are
10 due to the high anisotropic electrical conductivity that
has become obtainable by the incorporation of special
electroconductive particles in small amounts and due to
the arbitrary compounding enabled thereby for the film
formation. Conceivably the shape of the electroconductive
15 particles is the main cause of the fact that the film
exhibits a high anisotropic conductivity with small
amounts of electroconductive particles. In other words,
the adhesive layer in application becomes fluid with
heat or pressure and each electroconductive particle
20 embedded in the surface layer of the film will be in one-
point contact with the surface of the conductor to be
bonded, so that the adhesive film sufficiently adapts
itself to the adhesion surface of the conductor and pro-
vides high bond strength. Electroconductive particles
25 in the surface layer take such configurations as to
readily contact with electroconductive particles present
on the deeper side, forming links in the thickness direc-
tion and as to have a little opportunity to contact with

1 other electroconductive particles in the plane direction,
whereby the anisotropic conductivity is obtained.

The following description refers to materials
used in the invention.

5 The electroconductive particles used in the
invention are metallic particles of 1 to 50 μm in diameter.
The ratio of the smallest diameter to the largest diameter
of each particle is 0.5 to 1.0. The particles are contain-
ed in the adhesive component in an amount of 0.1 to 10%
10 by volume. The maximum particle size is desirably 1 to
50 μm , more preferably 1 to 10 μm . When it is less than
1 μm , a larger amount of electroconductive particles are
required, which results in deteriorating the bond strength
greatly. When the maximum particle size is more than
15 50 μm , it is impossible to obtain a smooth adhesive surface
having good affinity to an adherend from the viewpoint of
thickness of the adhesive film layer, which results in
failing to give sufficient adhesiveness. Further, insulat-
ing properties and resolution properties at electric
20 conduction are also undesirably worsened.

As regards the shape of the electroconductive
particles, the ratio of the smallest diameter to the
largest of each particle (hereinafter referred to as
"the aspect ratio") is about 0.5 to 1.0 as stated above.

25 If the aspect ratio is out of the above range, the balance
between the electroconductivity and the adhesiveness will
be disturbed. A typical example of the particle shapes
satisfying the above condition is spherical or nearly

1 spherical. However, the shape is not particularly limited
so long as the aspect ratio falls in the above range.
The particles are allowed to have projections or depres-
sions on the surface.

5 The particle size herein means the average
diameter of all the particles.

The shape and diameter of the particles are
conveniently measured by way of, for example, an electron
microscope.

10 When the electroconductive particles are, for
example, spherical, the adhesive layer is fluidized by the
heating or pressure at the time of adhesion, which results
in making it possible to contact one point of the special
particles with the conductor surface.

15 In contrast to this, flaky conductive particles,
for example, are aligned with longer axes thereof being
directed in parallel to the adhesive surface in the steady
state and the adherend surface is therefore occupied
mostly with the electroconductive particles, thereby the
20 adhesive properties are lowered to a large extent.

The electroconductive particles can be produced
by any possible method from the following materials:
Metals, for example, Ni, Fe, Cr, Co, Al, Sb, Mo, Cu, Ag,
Pt, and Au, and alloys and oxides of these metals. The
25 above materials may be used alone or in combination.

It is also possible to use metal-coated particles
of non-conductive materials, for example, glass and
plastics.

1 Suitable content of conductive particles in the
adhesive component layer is 0.1 to 10% by volume. The
thickness of the adhesive film is at least 110% of the
average particle size of the electroconductive particles
5 contained and desirably not more than 100 μ m. With the
particle content less than 0.1% by volume, no satisfactory
electrical conductivity is obtained, and when the content
exceeds 10% by volume, the bond strength much lowers and
no sufficient transparency of the film is obtainable.

10 The following description refers to compounding
for the adhesive film.

For selecting the polymer used for the adhesive,
some considerations are necessary depending upon the method
of applying the adhesive film, in other words, depending
15 upon whether the film is of heat sensitive type or of
pressure sensitive type. The heat sensitive type of
adhesive film is applied by heating to soften and flow on
the adherend surface, thereby bonding the object. For the
film of heat sensitive type, a polymer relatively hard
20 at ordinary temperatures is used. On the other hand, the
pressure sensitive type of adhesive film, which is applied
with pressure on an adherend, is relatively soft to such
an extent that stickiness thereof is perceptible even at
ordinary temperatures.

25 As the heat sensitive type of adhesive film,
various polymers can be adapted while thermoplastic
polymers that exhibit plasticity on heating are usually
employed as a main component. These polymers include,

1 for example, an ethylene-vinyl acetate copolymer, poly-
ethylene, ethylene-propylene copolymer, ethylene-acrylate
copolymer, acrylic rubber, polyisobutylene, atactic poly-
propylene, poly(vinyl butyral), styrene-butadiene copolymer,
5 polybutadiene, ethyl-cellulose, polyamide, and poly-
urethane. These polymers may be used alone or as a
mixture thereof.

As the pressure sensitive type of adhesive
film, polymers exhibiting stickiness even at ordinary
10 temperatures can be employed. These polymers include an
acrylic rubber, natural rubber, silicone rubber, poly-
chloroprene, butadiene-styrene copolymer, ethylene-vinyl
acetate copolymer, polyisobutylene, and poly(vinyl ether)
rubber. These polymers also may be used alone or as a
15 mixture thereof.

In addition to these polymers, tackifiers and
conventional additives such as plasticizers, crosslinking
agents, and antioxidants can be used, if necessary, for
either the heat sensitive type or the pressure sensitive
20 type. Suitable tackifiers for use herein include, for
example, rosin family resins such as rosin, hydro-rosin,
ester gum, and maleic acid-modified rosin, petroleum
resin, xylene resin, and cumarone-indene resin. These
tackifiers may be used alone or as a mixture thereof.

25 For compounding materials for the adhesive
film, a mixture of the polymer and additives, which are
used as required, is either dissolved in a solvent or
fused to liquid form, and mixed with electroconductive

1 particles by a conventional method such as stirring. Thus,
an electroconductive adhesive composition is obtained.

In this case, a surfactant, for example, can be
used, if required, as a dispersing agent for the electro-
5 conductive particles.

The above electroconductive adhesive composition
can be coated on paper, plastic film, or the like, which
is coated with a separator if necessary for helping the
later separation of the adhesive film, by means of a roll
10 coater or the like, followed by drying, or by hot melt
coating to give an electroconductive adhesive film. In
the case of the heat sensitive type that does not exhibit
stickiness at room temperature, the adhesive layer alone
without using such a separator can be wound up into a
15 roll or folded up.

The thickness of the adhesive film is decided
by considering the relation to the diameter of the electro-
conductive particles used and characteristics of the film.

That is, the thickness needs to be at least
20 110% of the particle size of the electroconductive
particles in order to hold the particles satisfactorily
in the adhesive. If the thickness is less than 110%,
some of the electroconductive particles will be protected
not completely with the adhesive, and in consequence will
25 be oxidized or corroded, thereby the electrical conducti-
vity being deteriorated. Also from the viewpoint of
characteristics of the adhesive film, the thickness is
required in the range of preferably 5 to 100 μm ,

1 particularly preferably 5 to 50 μm . When the thickness
is less than 5 μm , no sufficient adhesiveness is obtained,
and the thickness more than 100 μm is impractical since
a large amount of electroconductive particles need to be
5 mixed in order to secure sufficient electrical conducti-
vity with such a thick film.

One or both sides of the formed adhesive film
may be covered with separator films if necessary for the
purpose of protecting from the adherence of dust or the
10 like. The adhesive film, when both sides thereof are
covered with separator films, can be continuously wound
up into a roll or folded up.

The thus obtained adhesive film has good
transparency. Transparent adhesive films are advantageous
15 in that quality control in the production process is
easy to practice in the assembly of display devices or
the like, such structures thereof can be designed that
the objects to bond can be seen through in bonding opera-
tions, and the adjustment of relative positions (herein-
20 after this adjustment is referred to as registration)
for bonding circuits is facilitated and thereby the film
application can be automated.

For connecting a pair of circuits by using the
adhesive film, the following facilities and techniques
25 can be used. In the case of the heat sensitive type of
adhesive film, the film is preliminarily attached onto
all the surfaces of connecting terminals on an adherent A,
a separator, if present on the film, is peeled off,

1 the connecting terminals on the other adherend B are
placed on the film face to face, and the bonding is
accomplished with a hot press or heat roll.

In the case of the pressure sensitive type,
5 customary bonding techniques such as compression between
rolls can be adopted.

The anisotropic-electroconductive film according
to the invention has a total light transmittance of at
least 40% as measured in accordance with JIS K-6714. This
10 is favorable since optical registration of the portions
to be bonded together is possible when at least one of the
circuit boards is a flexible printed circuit board that
comprises a circuit formed on a transparent film.

The outline of such registration is illustrated
15 below referring to Fig. 3. In Fig. 3, 1 denotes an
anisotropic-electroconductive adhesive film according to
the invention which is interposed between the upper circuit
board 9 having connecting terminals 8 and the lower
circuit board 11 having connecting terminals 10. As a
20 light source 12, a usual electric lamp or fluorescent lamp
can be used, preferably provided with a condenser, but
the particularly preferred light source is a laser from
the viewpoint of lineality of light.

While the base materials of the circuit board
25 9 and 10 are preferably both transparent, at least the
circuit board 9 on the light source 12 side is required
to be transparent.

Light from the light source 12 enters the upper

1 circuit board 9, where the incident light is modified
into a pattern of light according to the opaque connecting
terminals 8, and the pattern of light is then passed
through the adhesive film 1 and reaches the lower circuit
5 board 11. Then, the lower circuit board 11 is moved in
parallel to the upper circuit board 9 so that the connect-
ing terminals 10 will be in agreement with the pattern
of light (the shadows of the terminals 8), for example,
by a driving means 13 provided with a photosensor. After
10 this registration of the upper and lower groups of connect-
ing terminals, both circuit boards 9 and 11 are pressed
with or without heating, thereby completing the bonding.

When both circuit boards are transparent, the
registration can also be accomplished by recording marks
15 14 and 15 for registration on the boards 9 and 11, respec-
tively, and utilizing light from the light source 12.

When the circuit board 11 is opaque, light from
the light source 12, after passing through the adhesive
film 1, reaches the circuit board 11, is converted into a
20 signal of reflected light according to the level difference
and reflectivity difference between the surface of the
circuit substrate 11 and the surface of the connecting
terminals 10. This reflected light passes through the
adhesive film 1 and the circuit board 9 to go out toward
25 the light source 12.

The registration can be accomplished by moving
the circuit board 11 by the driving means 13 provided
with a photosensor so that the reflected light signal

1 will be in accordance with the connecting terminals 8.

The invention is illustrated in further detail referring to the following examples. In the examples, "parts" and "%" are by weight unless otherwise noted; the
5 compounding proportions for adhesives are expressed in terms of solids; results obtained are all shown in Tables 1 and 2; referring to metal particle sizes, the aspect ratio of the specimen was determined from the respective mean values of the maximum diameters and minimum diameters
10 measured by a scanning electron microscope on 10 or more of the specimen particles; and the particle size was represented by the mean value of said maximum diameters.

Examples 1 and 2

15 An ethylene-vinyl acetate copolymer (mfd. by Mitsui Polychemicals Co., Ltd. under the tradename of Elvax 560; vinyl acetate content 4%, MI 3.5) and a rosin-base tackifier (mfd. by The Japanese Geon Co., Ltd. under the tradename of Quinton B-170; softening point 70°C) were each dissolved in toluene, respectively, to a concentration
20 of 20%.

Both the solutions (100 parts and 100 parts) were mixed, and in two portions of this mixture were added silver-coated glass beads (supplied by Toshiba-Ballotini Co., Ltd. under the tradename of Silver Beads S-3000S-3;
25 spherical shape, particle size 45 μ m, aspect ratio 0.95) to different concentrations. The mixtures were stirred to prepare adhesive compounded liquids. Each

1. compounded liquid was applied on a separator film (a 25- μ m
thick poly(ethylene terephthalate) film surface-treated
with a silicone) by means of bar coater so as to give a
dry thickness of 50 μ m. The coats were dried at 120°C
5 for 3 minutes to remove toluene to form adhesive films.
A metal plate (SUS-430BA, 500 μ m thick) and a copper foil
35 μ m thick were bonded together with each adhesive film
thus obtained. That is, each adhesive film was applied on
one SUS-430BA sheet, the separator film was peeled off,
10 and one copper foil was bonded onto the stripped surface
of the adhesive by using a pair of heat rolls (heated to
120°C). Properties of the films and results of the bonding
are shown in Table 1.

From these results, it is proved that adhesive
15 strength and thickness-directional conductivity sufficient
for practical use could be obtained by simple bonding
operation using the above films. In addition, these films
were found to have considerably high transparency, that is,
the total light transmittance was 40% or more, since
20 contents of the electroconductive particle were low.

Comparative Example 1

An adhesive film was prepared in the same manner
as in Examples 1 and 2 except that the content of the
electroconductive particle was increased to 20% by volume.

25 In this case, the adhesiveness was by far
inferior though the conductivity was good. The total
light transmittance of the adhesive film was 20% and

1 the low clarity was also ascertained by visual observation.

Examples 3 to 5

Adhesive films were prepared by following the
5 procedure of Examples 1 and 2, but the materials used and the thickness of the coats were varied and the coating was carried out by means of a hot-melt applicator (without using any solvent).

That is, a styrene-butadiene block copolymer
10 (mfd. by Asahi Chemical Industry Co., Ltd. under the tradename of Toughprene A, hereinafter designated as SBR; MI 2.6) and an aromatic tackifier (mfd. by Mitsui Petrochemical Industries Co., Ltd., tradename, Petrosin #150; softening point 150°C) were employed. The compound-
15 ing ratio of the SBR to the tackifier was 100 parts : 50 parts. The conductive particle used was a nickel powder (supplied by International Nickel Co. under the tradename of Carbonyl 123; spherical shape, average particle size 4.5 μ m, fine projections and depressions were present
20 throughout the surface, aspect ratio 0.70).

The SBR and the tackifier (the above compounding ratio) were fed into a melt mixer attached to the hot-melt applicator and were melted by heating. Said conductive particle was added to the melt, and coating films of dif-
25 ferent thicknesses were prepared. The evaluation of the thus prepared adhesive films was conducted in the same manner as in Examples 1 and 2 except that the application

1 of films for bonding was carried out with a hot press
(temperature of object: 160°C, pressure 2 kg/cm², press
time 5 seconds). All the obtained adhesive films showed
considerably high transparency.

5 Results of the evaluation, as shown in Table 1,
indicated that all the films had high adhesive strength
and exhibited low resistance characteristics.

The resistivities in the plane direction were
higher by several orders than those in the thickness
10 direction, showing high anisotropy in electroconductivity.

Comparative Example 2

An adhesive film was prepared in the same manner
as in Examples 3 to 5 except that the thickness of the
coat was made 150 μm. The resistivity in the thickness
15 direction was as high as 10⁸ Ω-cm. The adhesive film
showed considerably low transparency.

Comparative Example 3

An adhesive film was prepared by following the
procedure of Example 4 but using a flaky nickel powder
20 (thickness 0.6 μm, largest diameter ca. 40 μm, aspect
ratio 0.015).

The film showed a very low adhesive strength
and a nearly isotropic electroconductivity.

Example 6

25 To a toluene solution of an adhesive compound

1 of 100 parts of a natural rubber (grade 1, masticated for
30 minutes) and 30 parts of a polyterpene resin (soften-
ing point 100°C), was added 2% by volume of an aluminum
powder (supplied by Toyo Aluminum Co., Ltd. under the
5 tradename of AC-2500; oval shape, particle size 30 μm ,
aspect ratio 0.5), and the mixture was well stirred.

In the same manner as in Examples 1 and 2, this
mixture was applied on a separator film of 100 μm in total
thickness which had been prepared by coating a glassine
10 paper substrate with a polyethylene layer and treating the
surface of the polyethylene layer with a silicone. The
coated separator was dried, giving an adhesive film 40 μm
thick.

Using this adhesive film, a 500- μm thick
15 stainless steel sheet (SUS 430BA) and a 35- μm thick copper
foil were bonded together by compressing with a pair of
rubber rolls.

In this case, the adhesive film showed high
stickiness at room temperature and could be applied with
20 simple operation. The resulting resistivity in the thick-
ness direction was as low as $10^{-2} \Omega\text{-cm}$.

The adhesive film was considerably transparent,
that is, the total light transmittance was 70%.

Example 7

25 An adhesive compound composed of 100 parts of
an acrylic polymer (mfd. by Toagosei Chemical Industry Co.,

- 1 Ltd. tradename, Aron S-1511) and of 1 part of a cross-linking agent (supplied by Nippon Polyurethane Co., Ltd. under the tradename of Colodate L) was mixed with 5% by volume of a silver powder (supplied by Fukuda Metal
- 5 Foil Co., Ltd. under the tradename of Silcoat Ag. C-BOB; spherical shape, particle size 1.9 μm , aspect ratio 0.5). From this mixture, an adhesive film 10 μm thick was prepared and evaluated in the same manner as in Example 6.
- 10 The film showed high stickiness and could be applied simply at room temperature by using a pair of rubber rolls. The resulting resistivity in the thickness direction was as low as $10^{-3} \Omega\text{-cm}$, and the transparency was sufficient for practical use.
- 15 In addition, the crosslinking agent incorporated into the adhesive gave high cohesion, that is, high heat resistance to the adhesive film.

Table 1

Example No.	Content of electroconductive particles (vol.%)	Thickness of adhesive film (μm)	Resistivity (Ω-cm)		Adhesive strength (kg/cm)	Total light transmittance (%)
			Thickness direction	Plane direction		
Ex. 1	0.1	50	1×10^2	3×10^8	2.4	70
Ex. 2	10	50	5×10^{-2}	4×10^6	1.8	40
Com.Ex.1	20	50	3×10^{-3}	3×10^{-2}	0.1	20
Ex. 3	2	5	4×10^{-3}	5×10^8	0.9	85
Ex. 4	2	30	2×10^{-1}	7×10^9	2.1	70
Ex. 5	2	100	6×10^3	3×10^{10}	2.8	50
Com.Ex.2	2	150	7×10^8	4×10^{11}	3.2	30
Com.Ex.3	2	30	2×10^3	4×10^3	0.2	40
Ex. 6	3	40	1×10^{-2}	5×10^9	0.8	70
Ex. 7	5	10	1×10^{-3}	1×10^3	0.4	60

1 Test methods for the characteristics shown in
Table 1 were as follows:

- 1) Resistivity in the thickness direction: A
stainless steel sheet (SUS-430 BA) and an aluminum foil
5 of 0.5 cm² in surface area were bonded together through
an adhesive film specimen so that the edge effect would
be eliminated, the resistance of the adhesive film in
the thickness direction was measured, and the found value
was converted into volume resistivity.
- 10 2) Resistivity in the plane direction: An adhesive
film specimen was bonded onto an insulating polyester
film of 50 μm in thickness, the resistance of the film
in the plane direction was measured at a specimen width
of 0.5 cm with the space between the electrodes being set
15 to 0.5 cm, and the found value was converted into volume
resistivity.

For converting the found resistance into volume
resistivity in the above 1) and 2), the following equation
was used:

$$\rho = \frac{SR}{l}$$

- 20 wherein ρ : volume resistivity (Ω-cm),
 S : cross-sectional area of specimen (cm²),
 R : found value of resistance (Ω), and
 l : space between electrodes (cm).

- 3) Adhesive strength: The 180°-degree peeling

1 method in accordance with JIS Z-0237 was applied. The
measurement was conducted at a peeling speed 50 mm/min.,
20°C, and 65% RH by using a copper foil bent by 90° degree.

4) Total light transmittance: This was measured
5 in accordance with JIS K-6714 using a digital turbidimeter
(Model NDH-20D of Nippon Denshoku Kogyo K.K.).

Examples 8 to 11 and Comparative Examples 4 and 5

The same ethylene-vinyl acetate copolymer and
the same rosin-base tackifier (softening point 70°C) as
10 used in Example 1 were dissolved in equal amounts in toluene
to prepare solutions of concentration 20%. A nickel
powder (particle shape: spherical, average particle
size: 4.5 μ m, aspect ratio: 0.70) having fine projec-
tions and depressions was mixed in the proportions shown
15 in Table 2 with the above solutions. The mixtures
were each ball-milled for 24 hours to give adhesive com-
pounded liquids. Each compounded liquid was applied on
a 25- μ m thick polyester film surface-treated with a
releasing agent by means of a bar coater so as to give
20 a dry thickness of 30 μ m, and was dried at 120°C for 3
minutes to remove the toluene. In this way, adhesive films
of different conductive particle contents were obtained.
Using each adhesive film, two flexible polyester circuit
boards (pitch of circuit lines: 0.1 mm, line width 0.05 mm)
25 were coupled together by opposing the boards through the
adhesive film, registering the circuits, and bonding
together each pair of opposing lines by compressing a pair

1 of heat rolls (120°C). Characteristics of the thus coupled
circuits are shown in Table 2.

These results revealed that bond strength and
thickness-directional conductivity both sufficient for
5 practical use could be obtained with simple bonding operation using the films containing the conductive particles
in concentrations of 0.1 to 10.0% by volume.

In addition, these films were found to have
considerably high transparency, that is, the total light
10 transmittance was 40% or more, since contents of the
conductive particles were low.

Comparative Example 6

An adhesive film was prepared in the same
manner as in Example 10 but using a flaky nickel powder
15 (particle shape: flaky, thickness 0.6 μm , largest diameter
ca. 40 μm , aspect ratio 0.015).

The film showed a very low bond strength and a
nearly isotropic electroconductivity.

Example 12

20 To a toluene solution of an adhesive compound
of 100 parts of a natural rubber (grade 1, masticated for
30 minutes) and 30 parts of a polyterpene resin (softening
point 100°C), was added 2% by volume of an aluminum
powder (particle shape: oval, particle diameter 10 μm ,
25 aspect ratio 0.5), and the mixture was well stirred.

In the same manner as in Example 8, this mixture

1 was applied on a separator film of 100 μm in total thick-
ness which had been prepared by coating a glassine paper
substrate with a polyethylene layer and treating the
surface of the polyethylene layer with a silicone. The
5 coated separator was dried, giving an adhesive film 20 μm
thick.

Using this adhesive film, two flexible circuit
boards (pitch of circuit lines: 0.2 mm, line width: 0.1 mm)
were coupled together in the same manner as in Example 8.

10 In this case, the adhesive film showed high
stickiness at room temperature and could be applied with
simple operation. The resulting resistivity in the thick-
ness direction was as low as $10^{-1} \Omega\text{-cm}$.

The adhesive film was considerably transparent,
15 that is, the total light transmittance was 70%.

Example 13

An adhesive compound composed of 100 parts of
an acrylic polymer and of 1 part of an isocyanate type
crosslinking agent was mixed with 10% by volume of a silver
20 powder (particle shape: spherical, particle size
0.5 μm , aspect ratio 0.9). From this mixture, an adhesive
film 10 μm thick was prepared and evaluated in the same
manner as in Example 12.

The film showed high stickiness and could be
25 applied simply at room temperature by using a pair of
rubber rolls. The resulting resistivity in the thickness
direction was $10^{-3} \Omega\text{-cm}$, and the transparency was sufficient

for practical use.

In addition, the crosslinking agent incorporated into the adhesive gave high cohesion, that is, high heat resistance to the adhesive film.

Table 2

Example No.	Electroconductive particles			Thick- ness of adhesive film (μm)	Resistivity ($\Omega\text{-cm}$)		Adhesive strength (Kg/cm)	Total light trans- mittance (%)
	Particle size (μm)	Aspect ratio	Amount added (vol%)		Thickness direction	Plane direction		
Com.Ex. 4	4.5	0.7	0.05	30	3×10^6	5×10^9	1.2	85
Ex. 8	"	"	0.1	"	7×10^2	1×10^8	1.3	85
Ex. 9	"	"	2.0	"	2×10^{-1}	8×10^7	1.0	69
Ex. 10	"	"	5.0	"	5×10^{-2}	4×10^7	0.8	63
Ex. 11	"	"	10.0	"	1×10^{-2}	5×10^6	0.6	44
Com.Ex. 5	"	"	20.0	"	2×10^{-3}	5×10^0	0.2	30
Com.Ex. 6	40	0.015	5.0	"	2×10^3	6×10^3	0.1	41
Ex. 12	10	0.5	2.0	20	1×10^{-1}	5×10^7	0.7	70
Ex. 13	0.5	0.9	10.0	10	1×10^{-3}	1×10^7	0.3	45

1 As described in detail hereinbefore, the
anisotropic-electroconductive adhesive film according to
the present invention exhibits sufficient anisotropic
electroconductivity due to a specified electroconductive
5 particle mixed and has high bond strength since the content
of the particle is as low as 0.1 to 10% by volume.

 Since the adhesive film is available in sheet
or film form, a stable electrical conductivity can be
constantly obtained, bonding operation therewith is simple
10 and can be completed in a short time, thus a considerable
reduction in process time being possible. Moreover, there
is no hazard of environmental pollution since bonding
operation with this film is feasible without using any
solvent. Furthermore, this film has good transparency
15 due to the low content of the electroconductive particle.
Accordingly, connection of circuits can be carried out by
an optical means with this film and therefore accurate
registration of circuits is possible. Having anisotropic
electroconductivity, this film can be applied to fine
20 circuits, and the bonding function of the film enables
the bonding and fixing of circuits simultaneously with
the registration. This makes possible automatic connection
of circuits, and thus the improvement of the registration
accuracy and much labor saving will become possible.

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CLAIMS

1. An anisotropic-electroconductive adhesive film comprising an adhesive component layer and electroconductive particles, characterized in that electroconductive particles having an average particle size of 1 to 50 μm and a ratio of the minimum particle diameter to the maximum particle diameter of each particle being 0.5 to 1.0 are included in an adhesive component in an amount of 0.1 to 10% by volume, and the thickness of the adhesive component layer is at least 110% of the average particle size of the electroconductive particles and not more than 100 μm .

2. An adhesive film according to claim 1, characterized in that the electroconductive particles have a specific resistance of $10^{-5} \Omega\text{-cm}$ or less and the adhesive component layer has a total light transmittance of 40% or more.

3. An adhesive film according to claim 1 or 2, characterized in that the adhesive component is a heat-sensitive adhesive component containing a thermoplastic polymer as a main component.

4. An adhesive film according to claim 3, wherein the thermoplastic polymer is an ethylene-vinyl acetate copolymer, a polyethylene, an ethylene-propylene copolymer, an ethylene-acrylate copolymer, an acrylic

rubber, a polyisobutylene, an atactic polypropylene, a poly(vinylbutyral), a styrene-butadiene copolymer, a polybutadiene, ethyl-cellulose, a polyamide, a polyurethane or a mixture thereof.

5. An adhesive film according to claim 1 or 2, characterized in that the adhesive component is a pressure-sensitive adhesive component containing a polymer having stickiness at room temperature.

6. An adhesive film according to claim 5, wherein the polymer is an acrylic rubber, natural rubber, a silicone rubber, a polychloroprene, a butadiene-styrene copolymer, an ethylene-vinyl acetate copolymer, a polyisobutylene, a poly(vinyl ether) rubber, or a mixture thereof.

7. An adhesive film according to any one of the preceding claims, wherein the adhesive film has a resistivity at the direction along the film layer of $10^6 \Omega$ -cm or more, the minimum insulating width of 0.05 mm, a resistivity at the direction of thickness of $10^3 \Omega$ -cm or less, and adhesive strength of 300 g/cm or more.

8. An adhesive film according to any one of the preceding claims, wherein the electroconductive particles are particles of Ni, Fe, Cr, Co, Al, Sb, Mo, Cu, Ag, Pt, Au or a mixture thereof, or glass or plastic particles coated with these metals.

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9. A method for connecting circuits comprising interposing an anisotropic-electroconductive adhesive film having a total light transmittance of at least 40% as measured in accordance with JIS K-6714, between two circuit boards which are provided with connecting terminals on the respective surfaces facing each other, at least one of the circuit boards being light-transmissible, optically adjusting the two circuits to proper relative positions and connecting together the opposing connecting terminals.

10. A method for connecting circuits according to claim 9, characterized in that the anisotropic-electroconductive adhesive film is one according to any one of claims 1 to 8.

FIG. 1

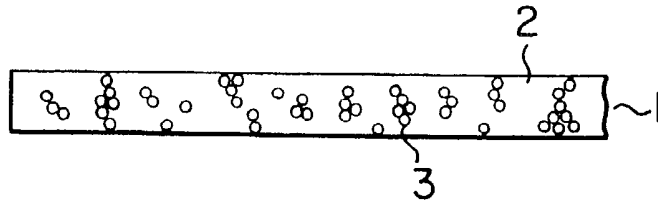


FIG. 2

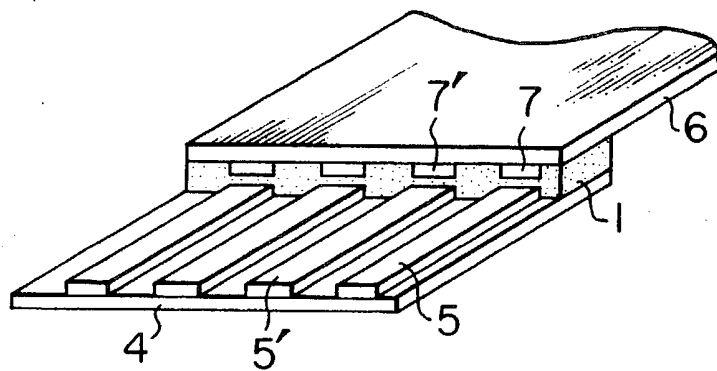


FIG. 3

